

Features

- RoHS compliant*
- ESD protection >25 kV
- Low capacitance <0.5 pF
- Low leakage current <50 nA

Applications

- HDMI 1.4
- Digital Visual Interface (DVI)
- USB 3.0 / USB OTG
- Memory protection
- SIM card ports

ChipGuard® MLC Series - ESD Protectors

General Information

The ChipGuard® MLC Series has been specifically designed to protect sensitive electronic components from electrostatic discharge damage. The MLC family has been designed to protect equipment to IEC61000-4-2, Level 4 (±8 kV Contact / ±15 kV Air Discharge) ESD specifications targeted for high speed USB 3.0/USB OTG, HDMI 1.4, DVI or IEEE1394 applications.

The ChipGuard® MLC Series has been manufactured to provide low 0.5 pF capacitance and leakage currents less than 5 nA with excellent clamp qualities, making the family almost transparent under normal working conditions.

Device Symbol



Electrical Characteristics @ 25 °C (unless otherwise noted)

D	0	CG0402MLC-								1114
Parameter	Symbol	3.3LG	05LG	12LG	24LG	3.3LGA	05LGA	12LGA	24LGA	Unit
Typical Continuous Operating Voltage	VDC	3.3	5	12	24	3.3	5	12	24	V
Typical Clamping Voltage (Note 1)	٧c					V				
Maximum Capacitance @ 1 VRMS 1 MHz	СО				C).5				pF
Maximum Leakage Current @ Max. VDC	ΙL	I <u>L</u> 5			nA					
Typical Trigger Voltage (Note 2)	VT	V _T 250				V				
Maximum Response Time	RT	R _T 1				ns				
ESD Protection: Per IEC 61000-4-2 Level 4 Min. Contact Discharge Min. Air Discharge Min. Air Discharge		±8 ±15 (Note 3) ±25					kV kV kV			
Operating Temperature	TOPR	-40 to +85 -40 to +125				°C				
Storage Temperature	TSTG	-55 to +150				°C				

D	CG0603MLC-							T		
Parameter	Symbol	3.3LE	05LE	12LE	24LE	3.3LEA	05LEA	12LEA	24LEA	Unit
Typical Continuous Operating Voltage	V _{DC}	3.3	5	12	24	3.3	5	12	24	V
Typical Clamping Voltage (Note 1)	٧c	25 25 25				V				
Maximum Capacitance @ 1 VRMS 1 MHz	CO	0.5					pF			
Maximum Leakage Current @ Max. VDC	ΙL	5	5 5 5			nA				
Typical Trigger Voltage (Note 2)	VT	250 250 250			V					
Maximum Response Time	RT	1				ns				
ESD Protection: Per IEC 61000-4-2 Level 4 Min. Contact Discharge Min. Air Discharge Min. Air Discharge		±8 ±15 (Note 3) ±25				kV kV kV				
Operating Temperature	TOPR	-40 to +85 -40 to +125			°C					
Storage Temperature	Teta	-55 to +150			°C					

Notes: 1. Per IEC 61000-4-2, Level 4 8 kV Contact Discharge. Measurement 30 ns after initiation of pulse.

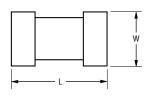
- ${\it 2. Per IEC 61000-4-2, Level 48 kV Contact Discharge. Measurement at maximum pulse voltage.}\\$
- 3. IEC 61000-4-2 ESD Performance will meet minimum 1000 reps without degradation in performance.

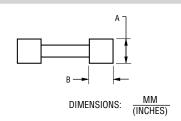


WARNING Cancer and Reproductive Harm - www.P65Warnings.ca.gov

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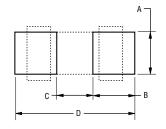
Product Dimensions





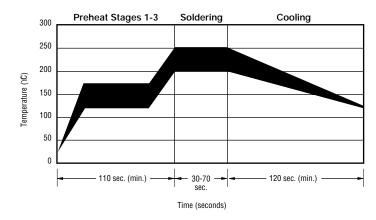
Dimension	CG0402 Series	CG0603 Series			
L	$\frac{1.00 \pm 0.15}{(0.04 \pm 0.006)}$	$\frac{1.60 \pm 0.20}{(0.064 \pm 0.008)}$			
W	$\frac{0.50 \pm 0.10}{(0.02 \pm 0.004)}$	$\frac{0.80 \pm 0.20}{(0.032 \pm 0.008)}$			
А	$\frac{0.36 \pm 0.05}{(0.014 \pm 0.002)}$	$\frac{0.45 \pm 0.10}{(0.018 \pm 0.004)}$			
В	$\frac{0.25 \pm 0.15}{(0.10 \pm 0.006)}$	$\frac{0.30 \pm 0.20}{(0.012 \pm 0.008)}$			

Recommended Pad Layout



Dim.	CG0402 Series	CG0603 Series
А	0.51 (0.020)	$\frac{0.76}{(0.030)}$
В	<u>0.61</u> (0.024)	1.02 (0.040)
С	<u>0.51</u> (0.020)	0.50 (0.020)
D	1.70 (0.067)	2.54 (0.100)

Solder Reflow Recommendations



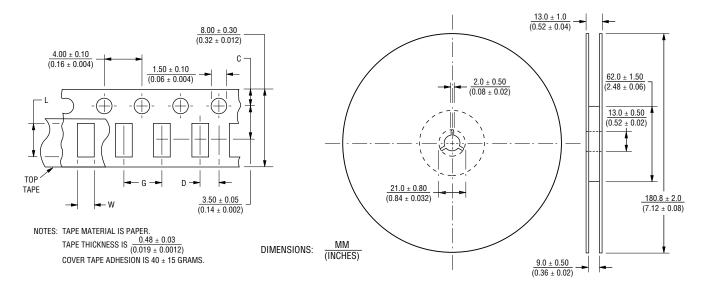
Α	Stage 1 Preheat	Ambient to Preheating Temperature	30 s to 60 s
В	Stage 2 Preheat	140 °C to 160 °C	60 s to 120 s
С	Stage 3 Preheat	Preheat to 200 °C	20 s to 40 s
D	Main Heating	200 °C 210 °C 220 °C 230 °C 240 °C 250 °C to 255 °C	60 s to 70 s 55 s to 65 s 50 s to 60 s 40 s to 50 s 30 s to 40 s 5 s
Е	Cooling	200 °C to 100 °C	1 °C/s to 4 °C/s

- This product can be damaged by rapid heating, cooling or localized heating.
- Heat shocks should be avoided. Preheating and gradual cooling recommended.
- Excessive solder can damage the device. Print solder thickness of 150 to 200 um recommended.
- Solder gun tip temperature should be kept below 280 °C and should not touch the device directly. Contact should be less than 3 seconds. A solder gun under 30 watts is recommended.

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Packaging Dimensions



Dimension	CG0402 Series	CG0603 Series
С	$\frac{1.75 \pm 0.05}{(0.04 \pm 0.002)}$	$\frac{1.75 \pm 0.10}{(0.04 \pm 0.004)}$
D	$\frac{2.00 \pm 0.02}{(0.08 \pm 0.0008)}$	$\frac{2.00 \pm 0.05}{(0.08 \pm 0.002)}$
L	$\frac{1.12 \pm 0.03}{(0.045 \pm 0.0012)}$	$\frac{1.80 \pm 0.20}{(0.072 \pm 0.008)}$
W	$\frac{0.62 \pm 0.03}{(0.025 \pm 0.0012)}$	$\frac{0.90 \pm 0.20}{(0.036 \pm 0.008)}$
G	$\frac{2.0 \pm 0.05}{(0.08 \pm 0.002)}$	$\frac{4.0 \pm 0.05}{(0.16 \pm 0.002)}$

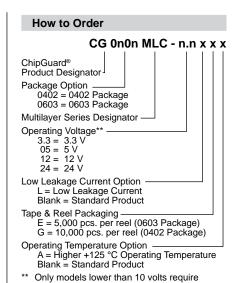
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decimal point.